

Abstract of the Disclosure:

A method for encapsulating the electronic component and a method for producing electronic components according to the method include coating the component with a coating material.

5 The coating material is hardened and an assembly including the component and the coating is encapsulated in plastic. In particular, the coating can be accomplished by immersion. The electronic component includes the coating encapsulation of a coating material applied in a flowable condition and hardened
10 and a plastic encapsulation encapsulating the coating.

GLM/kf